PRESS RELEASE

Pan-European Project to Help Innovative Companies Design and Build New Cyber-physical Systems Products for IoT Markets

15 EuroCPS Members from Nine Countries Will Assemble Networks for One-stop-shop Services to Ease Product Development and Create Jobs for European Companies

GRENOBLE, France – March 27, 2015 – CEA-Leti, coordinator of the pan-European consortium EuroCPS, today announced that the 15 partners have set up the goals of their collaborative project to establish a network of design centers to help SMEs and large companies develop innovative products for emerging Internet of Things (IoT) markets. The group will use proven cyber-physical system (CPS) platforms and working with research technology organizations (RTOs) or technology transfer-oriented university institutes who cluster a wide spectrum of technical and application knowledge to support innovation.

Funded by the European Commission, the three-year, €9.2 million project is designed to help innovators (SMEs and large companies) overcome barriers they face when entering new markets because they lack both knowledge of the value chain and the skills to master the entire design process from ideas to products. To that end, EuroCPS partners will provide technical expertise, coaching and access to advanced industrial CPS platforms to get innovators up to speed on the innovation ecosystem of "smart" products by facilitating access to the latest technologies and their implementation. In the process, it will offer all the necessary expertise and competencies to provide innovators from any sector with a smooth path to building innovative CPS-enabled systems. It also will tap existing regional ecosystems in several countries to bring the full value chain – from hardware/software platforms to cyber-physical systems – to high value-added products and services.

"EuroCPS will create synergies between emerging and established organizations operating in the CPS sector," said Marie-Noëlle Semeria, CEO of Leti "From that foundation, it will leverage the existing ecosystem to bring the full value chain from micro-electronics, smart systems and CPS to high value-added products and services. This combination will centralize in one project all the necessary expertise and competencies to provide SMEs from any sector with a one-stop-shop opportunity to build innovative CPS-enabled systems."

As ICT becomes increasingly integrated into our everyday environment, the design of embedded ICT from components to CPS becomes more important than ever, not only for the ICT supply industry but also for all major mainstream sectors of the economy. Embedded systems and more particularly CPS are key enablers of innovation in European industry, and SMEs are the primary drivers of job creation. By integrating SMEs into the CPS sector and helping them develop innovative products more rapidly, EuroCPS is expected to foster job growth and create sustained demand for European manufacturing, especially as the IoT creates demand for new products.

One key goal of the project is to link software, system and nano-electronic industries along the full CPS value chain to demonstrate a new cooperation model. This will be demonstrated by 30 novel industrial experiments funded through three open calls for developing innovative CPS products that will help increase the competitiveness of the European innovative companies. The targeted products will be designed, constructed and built on the EuroCPS Platforms:

- Avionics platform provided by Thales
- Connectivity platform provided by Schneider
- INEMO platform provided by STMicroelectronics
- Integrated and open platform provided by AVL
- Power management platform provided by Infineon
- Quark platform provided by Intel
- Silicon processes and package technology platform provided by STMicroelectronics
- STM32F platform provided by STMicroelectronics

EuroCPS members are major European system suppliers, world-class research centers and technology providers, all rooted in the top European regional ecosystems. Based on this strong foundation in European and national initiatives, EuroCPS willsignificantly reduce development time and certification efforts, thus putting Europe at the cutting edge of CPS development and implementation. It will do this through pan-European collaboration and knowledge exchange and access to the strong value chain in the strategic sector.

EuroCPS Project members:

- CEA-Leti, coordinator (France)
- CEA-List (France)
- STMicroelectronics Grenoble 2 SAS (France)
- Thales SA (France)
- AVL LIST GmbH (Austria)
- Infineon Technologies Austria AG (Austria)
- Fraunhofer-Gesellschaft zur Förderung der angewandten Forschung E.V. (Germany)
- The Digital Catapult (UK)
- Alma Mater Studiorum – University of Bologna (Italy)
- Lulea Tekniska Universitet (Sweden)
- Budapesti Muszaki es Gazdasagtudomanyi Egyetem (Hungary)
- Intel Shannon Limited (Ireland)
- Schneider Electric Industries SAS (France)
- Vereniging High Tech NL (The Netherlands)
- Finepower GmbH (Germany)
- STMicroelectronics SRL (Italy)

EuroCPS is part of the Smart-Anything-Everywhere Initiative under Horizon 2020 Leadership in Enabling Industrial Technologies which aims to generate new and breakthrough technologies, boost competitiveness, create jobs and support growth by offering a European-wide network of design centers. A first group of four innovation actions will combine efforts under the 25M€ funding budget to support around 100 industrial experiments with the aim of involving more than 200 SMEs and midcaps in the field of cyber-physical systems (CPS), Internet of Things (IoT) and smart systems integration (SSI).

More details on available competences, platforms and design centers are available at www.eurocps.org

About CEA-Leti (France)

By creating innovation and transferring it to industry, Leti is the bridge between basic research and production of micro- and nanotechnologies that improve the lives of people around the world. Backed by its portfolio of 2,200 patents, Leti partners with large industrials, SMEs and startups to tailor advanced solutions that strengthen their competitive positions. It has launched more than 50 startups. Its 8,000m² of new-generation cleanroom space feature 200mm and 300mm wafer processing of micro and nano solutions for applications ranging from space to smart devices. Leti's staff of more than 1,700 includes 200 assignees from partner companies. Leti is based in Grenoble, France, and has offices in Silicon Valley, Calif., and Tokyo. Follow us on www.leti.fr and @CEA_Leti.

Contact

Leti	Olivier Thomas	+33 4 38 78 29 54	olivier.thomas@cea.fr
Agency	Sarah-Lyle Dampoux	+33 1 39 43 82 30	sldampoux@mahoneylyle.com